



Product Change Notification

Change Notification #: 114744 - 00

**Change Title: Intel® Storage System JBOD2312S2SP
PCN 114744 - 00
Label
Regulatory and Safety Labels**

Date of Publication: July 1, 2015

Key Characteristics of the Change:

Labels

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 14, 2015
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Description of Change to the Customer:

Intel is implementing the following change on the Intel® Storage System JBOD2312S2SP:

1. Update the Common Regulatory Label using new EAC logo instead of GOST logo.
2. Update the Common Regulatory Label on the Outer Carton using new EAC logo instead of GOST logo.

See images below

Common Regulatory Label: New EAC logo instead of GOST for certification update.

Current label:



To Be label:



Common Regulatory Label on the Outer Carton: New EAC logo instead of GOST for certification update.

Current label:



To Be label:



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
JBOD2312S2SP	927043	G79990-003	G79990-004

PCN Revision History:

Date of Revision:

July 1, 2016

Revision Number:

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Reason:

Originally Published PCN



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114744-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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